

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	58	(lid or cover or heatsink or heat near sink) same (adhesive or interface) near5 (holes or voids or grooves or channel or trench or bubbles or gap) near10 solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 08:42
S1	15204	(lid or cover or heatsink or heat near sink) near8 (solder\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 08:41
S2	578	(chip or die or integrated adj circuit) near10 (lid or cover or heatsink or heat near sink) near8 (solder\$4) and (solder\$3) near5 (openings or voids or holes or apertures or missing or removed or removal or absent or air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 09:35
S3	248	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (lid or cover or heatsink or heat near sink) near5 (solder\$4) near10 (openings or voids or holes or apertures or missing or absent or air)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 09:44
S4	38	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (lid or cover or heatsink or heat near sink) near10 (solder\$4) near10 (thermal near interface or tim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 09:48
S5	49	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (solder\$4) near10 (thermal\$2 near interface or tim or thermal\$2 near adhesive) and (void or hole or opening or aperture or bubble or air or cavity) near5 (solder or tim or thermal near interface or thermal near adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 10:55
S6	2	("5298791"   "5658831").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/17 09:57
S7	26	("5658831").URPN.	USPAT	OR	ON	2005/08/17 09:58
S8	58	("2734154"   "4034468"   "4034469"   "4233645"   "4254431"   "4299715"   "4323914"   "4398975"   "4435611"   "4466483"   "4473113"   "4607277"   "4806111"   "4915167"   "4966142"   "5011787"   "5031308"   "5037312"   "5056706"   "5071787"   "5074947"   "5086558"   "5097387"   "5131582"   "5148141"   "5148265"   "5148266"   "5164566"   "5170930"   "5196371"   "5198189"   "5223747"   "5237130"   "5323265"   "5323294"   "5328087"   "5367435"   "5410449"   "5445308"   "5455390"   "5459352"   "5542602"   "5553769"   "5557501"   "5561590"   "5572404"   "5611884"   "5651179"   "5658831"   "5688721"   "5720100"   "5745344"   "5808874"   "5819406"   "5920125"   "5975408"   "6000127").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/17 10:05
S9	0	("6202298").URPN.	USPAT	OR	ON	2005/08/17 10:16
S10	14	("4034468"   "4034469"   "4750086"   "5021924"   "5247426"   "5510650"   "5591789"   "5604978"   "5650662"   "5712448"   "5757073"   "5790376"   "5844310"   "5847929").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/17 10:21
S11	3	("6396700").URPN.	USPAT	OR	ON	2005/08/17 10:23
S12	9	("5715684"   "6000225"   "6230497"   "6250085"   "6282907"   "6396700"   "6424533"   "6489551"   "6548894").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/17 10:24
S13	455	(chip or die or integrated adj circuit) and (lid or cover or heatsink or heat near sink) same (solder\$4) same (wetting or wettable or wetted)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 10:44

S14	65	(chip or die or integrated adj circuit) and (lid or cover or heatsink or heat near sink) same (solder\$4) same (non-wett\$4 or nonwett\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 10:44
S15	24	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (solder\$4) near10 (thermal\$2 near interface or tim or thermal\$2 near adhesive) and (trench or groove or gap) near5 (solder or tim or thermal near interface or thermal near adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 11:13
S16	2	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (solder\$4) near10 (thermal\$2 near interface or tim or thermal\$2 near adhesive) and (patterned or patterning) near5 (solder or tim or thermal near interface or thermal near adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 10:59
S17	38	(solder) near6 (pattern\$4 or control\$4 or non-wett\$4 or nonwett\$4 or position\$4) near15 (copper or cu) near8 (nickel near gold or niau or auni or ni near au)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 11:05
S18	58	(solder) near6 (reflow\$4) near10 (nonwett\$4 or non-wett\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 11:06
S19	4	(chip or die or integrated adj circuit) near4 (lid or cover or heatsink or heat near sink) and (solder\$4) near10 (thermal\$2 near interface or tim or thermal\$2 near adhesive) and (channel) near5 (solder or tim or thermal near interface or thermal near adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 11:15
S20	53	438/117.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:06
S21	54	438/119.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 15:59
S23	134	solder near4 flux\$4 near5 solvent and (solder near ball or solder near bump or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 15:38
S24	14	liquid near2 flux\$4 near6 (solvent or alcohol) and (solder near ball or solder near bump or bga or ball near grid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 15:38
S25	198	438/122.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 16:23
S26	185	257/704.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 16:39
S27	297	257/706.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 17:00

S28	135	257/707.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 17:00
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